



Material Content Data Sheet



Sales Product Name		BSZ060NE2LS		Issued		27. September 2017		
MA#		MA001002364						
Package		PG-TSDSON-8-25		Weight*		35.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.182	0.52	0.52	5156	5156
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70	
	non noble metal	zinc	7440-66-6	0.010	0.03		279	
	non noble metal	iron	7439-89-6	0.197	0.56		5575	
wire	non noble metal	copper	7440-50-8	7.988	22.64	23.24	226366	232290
	noble metal	gold	7440-57-5	0.030	0.09	0.09	856	856
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1088
encapsulation	plastics	epoxy resin	-	1.977	5.60		56012	
	inorganic material	silicondioxide	60676-86-0	17.176	48.65	54.36	486701	543801
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11201	11201
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	576	576
solder	noble metal	silver	7440-22-4	0.008	0.02		228	
	non noble metal	tin	7440-31-5	0.006	0.02		182	
	non noble metal	lead	7439-92-1	0.307	0.87	0.91	8702	9112
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2663	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.81	11.09	108132	110961
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
heat sink CLIP	non noble metal	iron	7439-89-6	0.073	0.21		2065	
	non noble metal	copper	7440-50-8	2.959	8.39	8.61	83853	86047
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com